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(71) Applicant: **INTEL CORPORATION** [US/US]; 2200 Mission College Boulevard, Santa Clara, CA 95052 (US).

(72) Inventors: **MU, Xiao-Chun**; 19685 Via Escuela Drive, Saratoga, CA 95070 (US). **MA, Qing**; 919 Brentwood Drive, San Jose, CA 95129 (US). **FUJIMOTO, Harry**; 1366 Los Arboles Avenue, Synnyvale, CA 94087 (US).

(74) Agent: **MALLIE, Michael, J.**; Blakely Sokoloff Taylor & Zafman, 12400 Wilshire Boulevard, Los Angeles, CA 90025 (US).

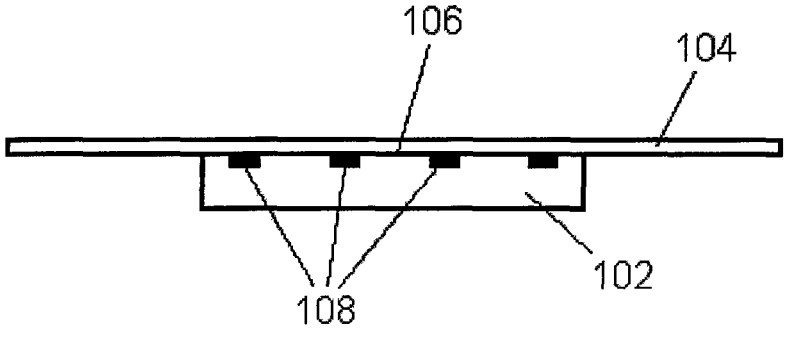
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(54) Title: DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE



(57) Abstract: A microelectronic package including a microelectronic die having an active surface and at least one side. An encapsulation material is disposed adjacent the microelectronic die side(s), wherein the encapsulation material includes at least one surface substantially planar to the microelectronic die active surface. A first dielectric material layer may be disposed on at least a portion of the microelectronic die active surface and the encapsulation material surface. At least one conductive trace is then disposed on the first dielectric material layer. The conductive trace(s) is in electrical contact with the microelectronic die active surface. At least one conductive trace extends adjacent the microelectronic die active surface and adjacent the encapsulation material surface.

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